



## Material Content Data Sheet



<b>Sales Product Name</b>		BSC0923NDI		<b>Issued</b>		3. June 2015		
<b>MA#</b>		MA001001398						
<b>Package</b>		PG-TISON-8-2		<b>Weight*</b>		96.57 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.603	0.62	0.62	6244	6244
leadframe	inorganic material	phosphorus	7723-14-0	0.010	0.01		106	
	non noble metal	zinc	7440-66-6	0.041	0.04		425	
	non noble metal	iron	7439-89-6	0.822	0.85		8508	
wire	non noble metal	copper	7440-50-8	33.360	34.54	35.44	345442	354481
	noble metal	gold	7440-57-5	0.061	0.06	0.06	637	637
	encapsulation	organic material	carbon black	1333-86-4	0.096	0.10		989
plastics	plastics	epoxy resin	-	4.920	5.09		50947	
	inorganic material	silicondioxide	60676-86-0	42.753	44.30	49.49	442698	494634
	leadfinish	non noble metal	tin	7440-31-5	1.122	1.16	1.16	11616
plating	noble metal	silver	7440-22-4	0.186	0.19	0.19	1924	1924
solder	noble metal	silver	7440-22-4	0.025	0.03		257	
	non noble metal	tin	7440-31-5	0.020	0.02		205	
	non noble metal	lead	7439-92-1	0.947	0.98	1.03	9806	10268
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.003	0.00		36	
	non noble metal	zinc	7440-66-6	0.014	0.01		144	
	non noble metal	iron	7439-89-6	0.279	0.29		2885	
	non noble metal	copper	7440-50-8	11.312	11.71	12.01	117131	120196
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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